# Analog Multiplexers/ Demultiplexers with Injection Current Effect Control

# **Automotive Customized**

These devices are pin compatible to standard HC405x and MC1405xB analog mux/demux devices, but feature injection current effect control. This makes them especially suited for usage in automotive applications where voltages in excess of normal logic voltage are common.

The injection current effect control allows signals at disabled analog input channels to exceed the supply voltage range without affecting the signal of the enabled analog channel. This eliminates the need for external diode/ resistor networks typically used to keep the analog channel signals within the supply voltage range.

The devices utilize low power silicon gate CMOS technology. The Channel Select and Enable inputs are compatible with standard CMOS outputs.

#### **Features**

- Injection Current Cross-Coupling Less than 1mV/mA (See Figure 9)
- Pin Compatible to HC405X and MC1405XB Devices
- Power Supply Range  $(V_{CC} GND) = 2.0 \text{ to } 6.0 \text{ V}$
- In Compliance With the Requirements of JEDEC Standard No. 7A
- Chip Complexity: 154 FETs or 36 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



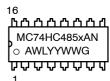
# ON Semiconductor®

http://onsemi.com

#### MARKING DIAGRAMS

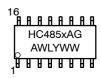


PDIP-16 N SUFFIX CASE 648





SOIC-16 D SUFFIX CASE 751B





SOIC-16 WIDE DW SUFFIX CASE 751G





TSSOP-16 DT SUFFIX CASE 948F



x = 1 or 2

A = Assembly Location

WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

# **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 12 of this data sheet.

#### X0 13 X1 X2<sup>15</sup> ANALOG INPUTS/ OUTPUTS MULTIPLEXER/ COMMON OUTPUT/ Х3-DEMULTIPLEXER INPUT X5 X6-11 CHANNEL 10 SELECT INPUTS С 6 ENABLE-PIN 16 = V<sub>CC</sub> PIN 8 = GND

Figure 1. MC74HC4851A Logic Diagram Single-Pole, 8-Position Plus Common Off

#### **FUNCTION TABLE - MC74HC4851A**

Conti	ol Inp			
	;	Selec	t	
Enable	С	В	Α	ON Channels
L	L	L	L	X0
L	L	L	Н	X1
L	L	Н	L	X2
L	L	Н	Н	X3
L	Н	L	L	X4
L	Н	L	Н	X5
L	Н	Н	L	X6
L	Н	Н	Н	X7
Н	Х	Χ	Χ	NONE

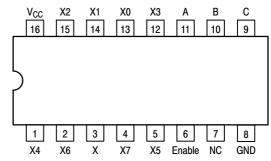


Figure 2. MC74HC4851A 16-Lead Pinout (Top View)

# 13 X X1 X SWITCH X2 15 Х3 ANALOG INPUTS/OUTPUTS COMMON **OUTPUTS/INPUTS** Y1 Y SWITCH A 10 CHANNEL-SELECT PIN 16 = V<sub>CC</sub> PIN 8 = GND INPUTS В ENABLE 6

Figure 3. MC74HC4852A Logic Diagram Double-Pole, 4-Position Plus Common Off

### **FUNCTION TABLE - MC74HC4852A**

Control Inputs				
	Select			
Enable	В	Α	ON Ch	annels
L	L	L	Y0	X0
L	L	Н	Y1	X1
L	Н	L	Y2	X2
L	Н	Н	Y3	X3
Н	X	Χ	NO	NE

X = Don't Care

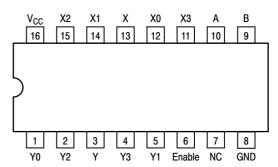


Figure 4. MC74HC4852A 16-Lead Pinout (Top View)

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Positive DC Supply Voltage (Referenced to GND)	-0.5 to + 7.0	V
V <sub>in</sub>	DC Input Voltage (Any Pin) (Referenced to GND)	$-0.5$ to $V_{CC}$ + 0.5	V
I	DC Current, Into or Out of Any Pin	±25	mA
P <sub>D</sub>	Power Dissipation in Still Air, Plastic DIP† SOIC Package† TSSOP Package†	750 500 450	mW
T <sub>stg</sub>	Storage Temperature Range	-65 to + 150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds Plastic DIP, SOIC or TSSOP Package	260	ç

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating – Plastic DIP: – 10 mW/°C from 65° to 125°C SOIC Package: – 7 mW/°C from 65° to 125°C

TSSOP Package: - 6.1 mW/°C from 65° to 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range GND  $\leq$  ( $V_{in}$  or  $V_{out}$ )  $\leq$   $V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage (Referenced to GND	2.0	6.0	V
V <sub>in</sub>	DC Input Voltage (Any Pin) (Referenced to GND	GND	V <sub>CC</sub>	V
V <sub>IO</sub> *	Static or Dynamic Voltage Across Switch	0.0	1.2	V
T <sub>A</sub>	Operating Temperature Range, All Package Types	- 55	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>		/ 0	1000 500 400	ns

<sup>\*</sup>For voltage drops across switch greater than 1.2 V (switch on), excessive  $V_{CC}$  current may be drawn; i.e., the current out of the switch may contain both  $V_{CC}$  and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded.

#### DC CHARACTERISTICS — Digital Section (Voltages Referenced to GND) VEE = GND, Except Where Noted

			v <sub>cc</sub>	Guaranteed Limit			
Symbol	Parameter	Condition	v	−55 to 25°C	≤85°C	≤125°C	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage, Channel-Select or Enable Inputs	R <sub>on</sub> = Per Spec	2.0 3.0 4.5 6.0	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	1.50 2.10 3.15 4.20	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage, Channel-Select or Enable Inputs	R <sub>on</sub> = Per Spec	2.0 3.0 4.5 6.0	0.50 0.90 1.35 1.80	0.50 0.90 1.35 1.80	0.50 0.90 1.35 1.80	V
I <sub>in</sub>	Maximum Input Leakage Current on Digital Pins (Enable/A/B/C)	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	± 0.1	± 1.0	± 1.0	μΑ
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	$V_{in(digital)} = V_{CC}$ or GND $V_{in(analog)} = GND$	6.0	2	20	40	μΑ

# DC CHARACTERISTICS — Analog Section

				Guara	nteed Lin	nit	
Symbol	Parameter	Condition	v <sub>cc</sub>	−55 to 25°C	≤ <b>85°C</b>	≤125°C	Unit
R <sub>on</sub>	Maximum "ON" Resistance	$V_{in} = V_{IL} \text{ or } V_{IH}; V_{IS} = V_{CC} \text{ to}$ GND; $I_S \le 2.0 \text{ mA}$	2.0 3.0 4.5 6.0	1700 1100 550 400	1750 1200 650 500	1800 1300 750 600	Ω
ΔR <sub>on</sub>	Delta "ON" Resistance	$V_{in}$ = $V_{IL}$ or $V_{IH}$ ; $V_{IS}$ = $V_{CC}/2$ $I_S \le 2.0$ mA	2.0 3.0 4.5 6.0	300 160 80 60	400 200 100 80	500 240 120 100	Ω
l <sub>off</sub>	Maximum Off-Channel Leakage Current, Any One Channel Common Channel	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	±0.1 ±0.1	±0.1 ±0.1	±0.1 ±0.1	μΑ
I <sub>on</sub>	Maximum On-Channel Leakage Channel-to-Channel	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	±0.1	±0.1	±0.1	μΑ

# AC CHARACTERISTICS ( $C_L$ = 50 pF, Input $t_r$ = $t_f$ = 6 ns)

Symbol	Parameter		−55 to 25°C	≤ <b>85</b> °C	≤125°C	Unit
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay, Analog Input to Analog Output		160 80 40 30	180 90 45 35	200 100 50 40	ns
t <sub>PHL</sub> , t <sub>PHZ,PZH</sub> t <sub>PLH</sub> , t <sub>PLZ,PZL</sub>			260 160 80 78	280 180 90 80	300 200 100 80	ns
C <sub>in</sub>	Maximum Input Capacitance Digital Pins (All Switches Off) Any Single Analog Pin (All Switches Off) Common Analog Pin		10 35 40	10 35 40	10 35 40	pF
C <sub>PD</sub>	Power Dissipation Capacitance Typical	5.0	20			pF

# INJECTION CURRENT COUPLING SPECIFICATIONS ( $V_{CC}$ = 5V, $T_A$ = -55°C to +125°C)

Symbol	Parameter	Condition	Тур	Max	Unit
$V\Delta_{out}$	Maximum Shift of Output Voltage of Enabled Analog Channel	$I_{in}^* \le 1 \text{ mA}, R_S \le 3.9 \text{ k}\Omega$	0.1	1.0	mV
		$I_{in}^* \le 10 \text{ mA}, R_S \le 3.9 \text{ k}\Omega$	1.0	5.0	
		$I_{in}^* \le 1 \text{ mA}, R_S \le 20 \text{ k}\Omega$	0.5	2.0	
		$I_{in}^* \le 10 \text{ mA}, R_S \le 20 \text{ k}\Omega$	5.0	20	

<sup>\*</sup> I<sub>in</sub> = Total current injected into all disabled channels.

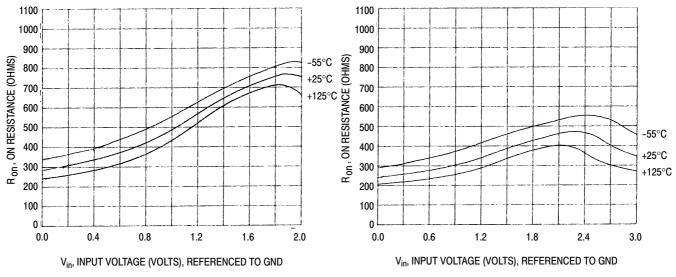


Figure 5. Typical On Resistance V<sub>CC</sub> = 2V

Figure 6. Typical On Resistance V<sub>CC</sub> = 3V

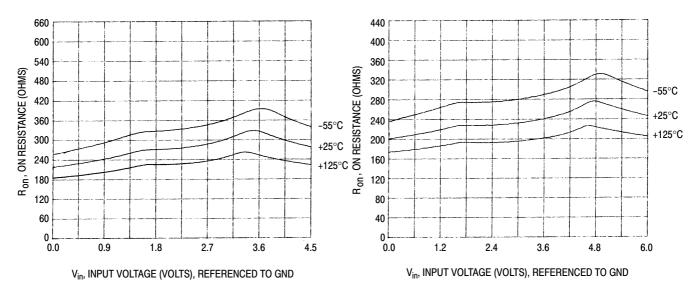


Figure 7. Typical On Resistance V<sub>CC</sub> = 4.5V

Figure 8. Typical On Resistance  $V_{CC} = 6V$ 

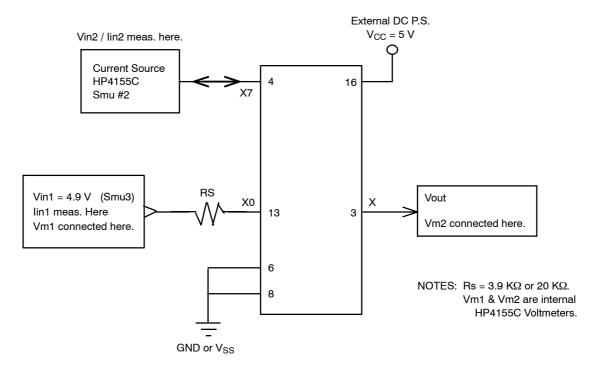


Figure 9. Injection Current Coupling Specification

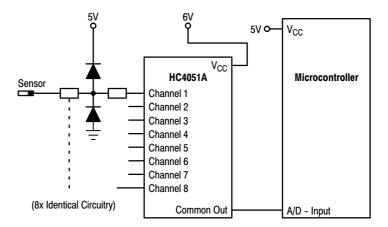


Figure 10. Actual Technology

Requires 32 passive components and one extra 6V regulator to suppress injection current into a standard HC4051 multiplexer

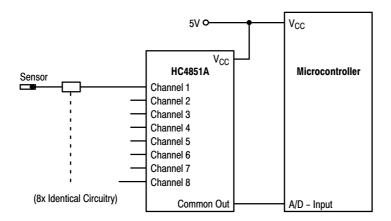


Figure 11. MC74HC4851A Solution
Solution by applying the HC4851A multiplexer

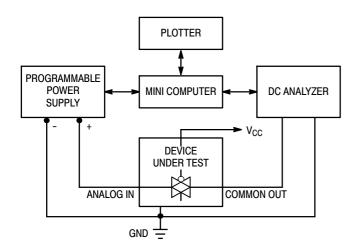


Figure 12. On Resistance Test Set-Up

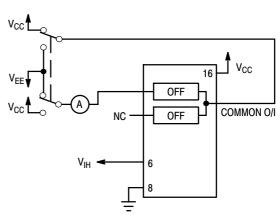


Figure 13. Maximum Off Channel Leakage Current, Any One Channel, Test Set-Up

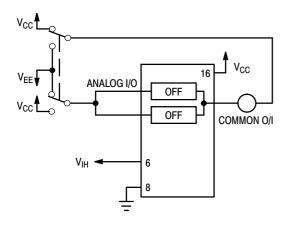


Figure 14. Maximum Off Channel Leakage Current, Common Channel, Test Set-Up

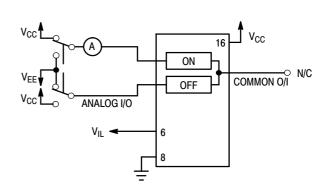


Figure 15. Maximum On Channel Leakage Current, Channel to Channel, Test Set-Up

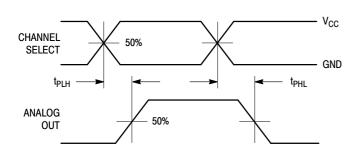
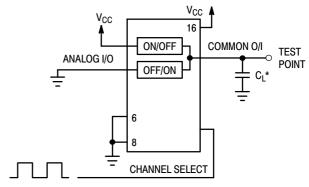


Figure 16. Propagation Delays, Channel Select to Analog Out



\*Includes all probe and jig capacitance

Figure 17. Propagation Delay, Test Set-Up Channel Select to Analog Out

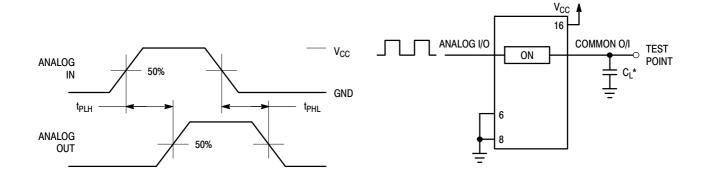


Figure 18. Propagation Delays, Analog In to Analog Out

Figure 19. Propagation Delay, Test Set-Up
Analog In to Analog Out

\*Includes all probe and jig capacitance

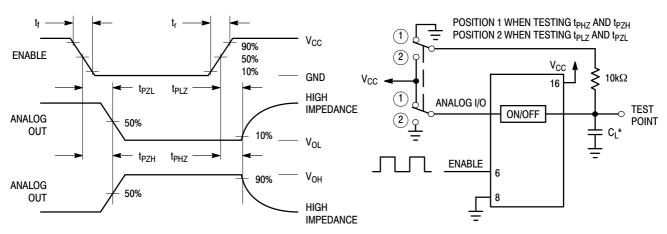


Figure 20. Propagation Delays, Enable to Analog Out

Figure 21. Propagation Delay, Test Set-Up Enable to Analog Out

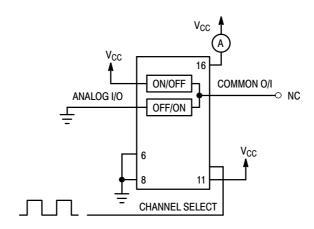


Figure 22. Power Dissipation Capacitance, Test Set-Up

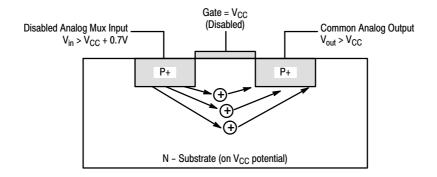


Figure 23. Diagram of Bipolar Coupling Mechanism

Appears if  $V_{in}$  exceeds  $V_{CC}$ , driving injection current into the substrate

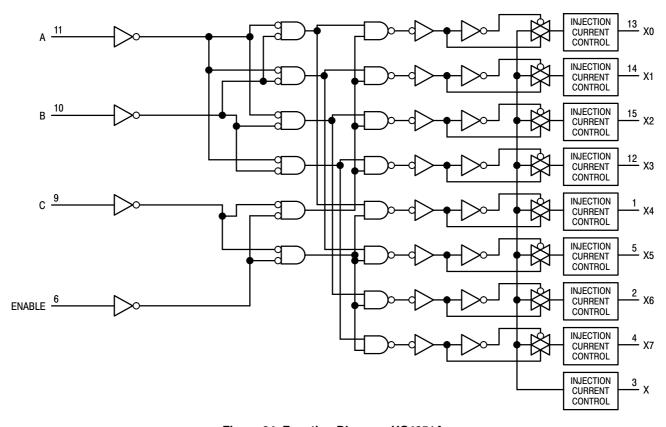


Figure 24. Function Diagram, HC4851A

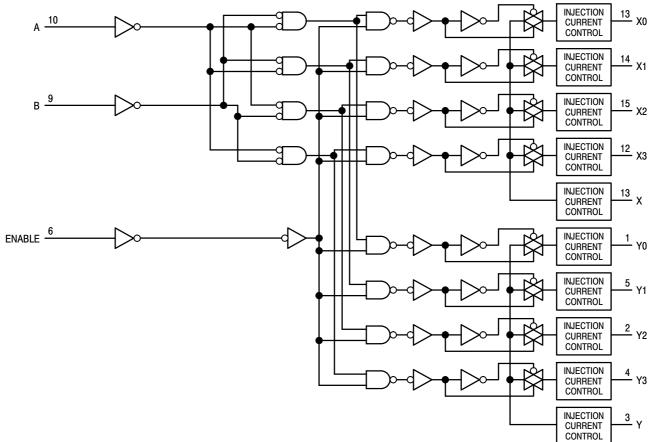


Figure 25. Function Diagram, HC4852A

## **ORDERING INFORMATION**

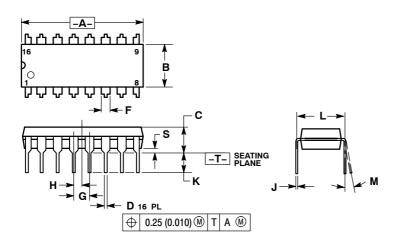
Device	Package	Shipping <sup>†</sup>
MC74HC4851ANG	PDIP-16 (Pb-Free)	500 Units / Box
MC74HC4851ADG		48 Units / Rail
MC74HC4851ADR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLVHC4851ADR2G*	(12.1135)	2500 Units / Tape & Reel
MC74HC4851ADTR2G	TSSOP-16	2500 Units / Tape & Reel
NLVHC4851ADTR2G*	(Pb-Free)	2500 Units / Tape & Reel
MC74HC4851ADWR2G	SOIC-16 WIDE (Pb-Free)	1000 Units / Tape & Reel
MC74HC4852ANG	PDIP-16 (Pb-Free)	500 Units / Box
MC74HC4852ADG		48 Units / Rail
MC74HC4852ADR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
NLV74HC4852ADR2G*	(FB-Free)	2500 Units / Tape & Reel
MC74HC4852ADTR2G	TSSOP-16	2500 Units / Tape & Reel
NLVHC4852ADTR2G*	(Pb-Free)	2500 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

# **PACKAGE DIMENSIONS**

PDIP-16 **N SUFFIX** CASE 648-08 **ISSUE T** 

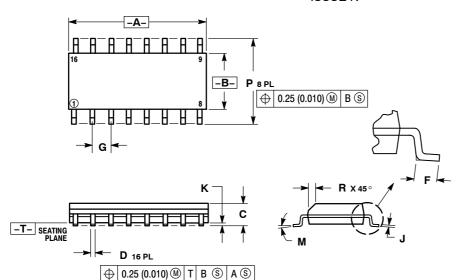


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54 BSC	
Н	0.050	BSC	1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
М	0°	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

#### PACKAGE DIMENSIONS

#### SOIC-16 **D SUFFIX** CASE 751B-05 ISSUE K



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

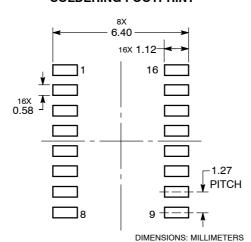
  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD

- DIMENSIONS A AND B DO NOT INCLUDE MOLEP PROTRUSION.

  MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

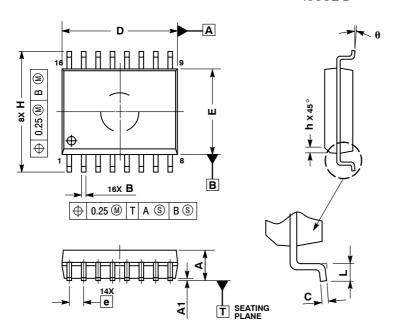
## **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

#### SOIC-16 WB **DW SUFFIX** CASE 751G-03 ISSUE D



- NOTES:
  1. DIMENSIONS ARE IN MILLIMETERS.
  2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.

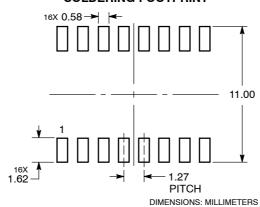
- MOLD PROTRUSION.

  4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

  5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

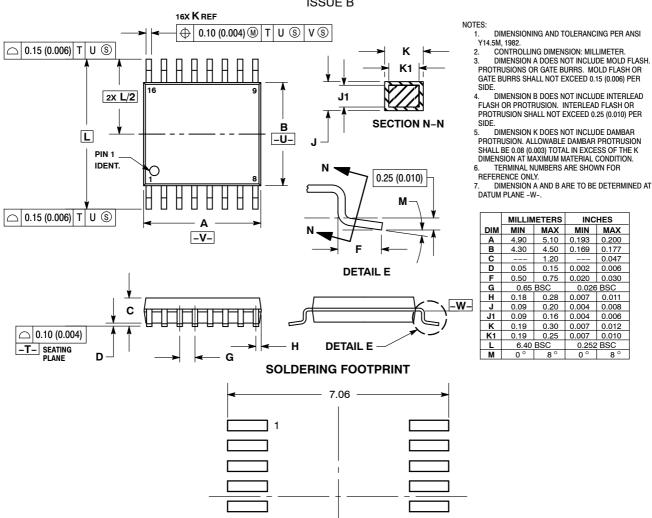
	MILLIMETERS		
DIM	MIN	MAX	
Α	2.35	2.65	
A1	0.10	0.25	
В	0.35	0.49	
С	0.23	0.32	
D	10.15	10.45	
Е	7.40	7.60	
е	1.27	BSC	
Н	10.05	10.55	
h	0.25	0.75	
L	0.50	0.90	
q	0 °	7 °	

#### **SOLDERING FOOTPRINT**



#### PACKAGE DIMENSIONS

#### TSSOP-16 **DT SUFFIX** CASE 948F **ISSUE B**



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ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

MC74HC4851A/D

INCHES

MIN MAX

0.026 BSC

0.252 BSC

0.004

0 °

0.65 **PITCH** 

**DIMENSIONS: MILLIMETERS** 

0.177

0.047

0.006

0.008

0.006